Update on radiation hardness of Silicon Diodes for the future CMS High Granularity Calorimeter (HGCAL)

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- High Granularity Calorimeter (HGCAL)
- HGCAL silicon sensors
- Results of the characterization after neutron irradiation:
  - ►IV, CV
  - ► CCE
  - MIP sensitivity
- Precision timing and test beam
- Summary and future activities



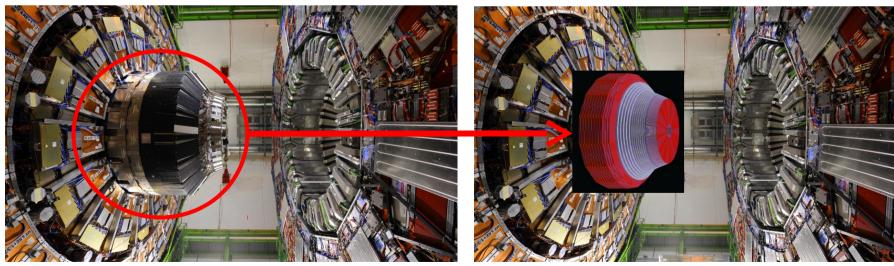
# **High Granularity Calorimeter (HGCAL)**

CMS needs to replace End-cap Electromagnetic and Hadronic calorimeters for Phase II due to radiation damage. This opens a new possibility for the Calorimeter design and the **HGCAL has been the technology chosen for this upgrade**.

We are working for the future implementation of the High Granularity Calorimeter with  $\sim$ 6M channels of silicon pads, integrating EE and HE functions (CALICE concept) with a Back HE to capture energy tails.

We expect that with such detailed information from the calorimeter, coupled with a precision silicon tracker, we will be able to measure physics objects with high precision.

#### **Current detector**



#### An Si Based HGC CMS at the HL-LHC



# **High Granularity Calorimeter (HGCAL)**

### **Major Engineering Challenges**

### ~600 m2 of Silicon in a high radiation environment.

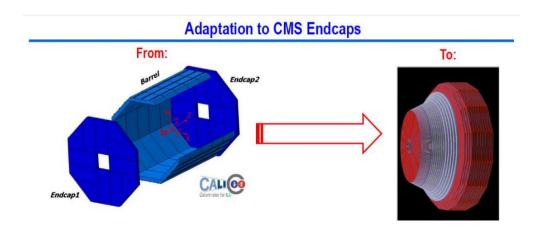
- ✓ Cost.
- ✓ Very high radiation levels need to plan for 1.5x10<sup>16</sup> neutrons/cm<sup>2</sup>

### Cooling.

- ✓ We need a compact calorimeter with small gaps between absorber plates.
- ✓ We need to operate at 30°C
- ✓ Total power is ~ 100 kW.

### **Data and Trigger**

- Channel count is 6M, with 21.5K detector modules and 40 Si planes. Producing an enormous amount of data.
- ✓ Data used in the Level- 1 CMS event trigger.





# **HGCAL Silicon sensors**

Tolerance study of large area pad diodes as active sensor for a High Granularity Electromagnetic Endcap Calorimeter for Phasell Upgrade

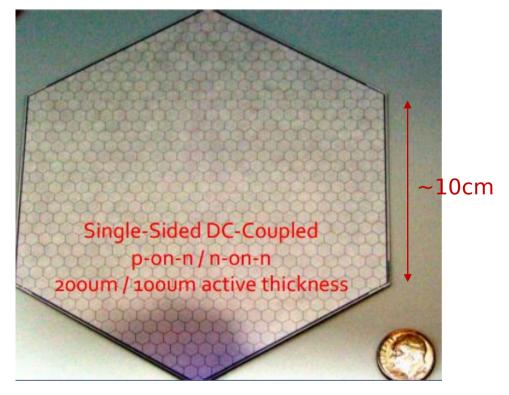
Investigate sensor performance after **neutron irradiation** with neutron equivalent fluences up to  $1.5 \cdot 10^{16}$  n/cm<sup>2</sup>

#### Sensors under investigation:

- Silicon growth technique (Epi: epitaxial layer, FZ: floating zone)
- Polarity: n-on-p (p-type), p-on-n (n-type)
- Active thickness:
  - ✓ FZ: 320, 200 and 120 um
  - ✓ Epi: 100 and 50 um
- ✓ Size:
  - ✓ Large diodes : 5 × 5 mm<sup>2</sup>
  - Small diodes : 2 × 2 mm<sup>2</sup>

### **HGCAL** operating conditions:

- ✓ Temperature (T) <  $-30 \circ C$ : ~  $-35 \circ C$
- ✓ Bias voltage (U): 600 ÷ 800 V





# **HGCAL Silicon sensors**

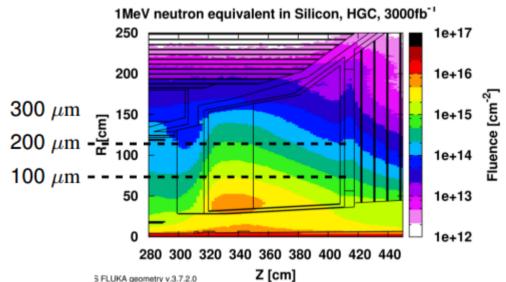
### **Available sensors**

- Sensors irradiated in Ljubljana
- Sensors initially measured at Hamburg 3 and then shipped to CERN
- P: bulk P (n-on-p)
- N: bulk N (p-on-n)

#### List of sensors, only Floating Zone:

Status during Hamburg measurements

		Thickness (um)	
Fluence n/cm <sup>2</sup>	320	200	120
4.00E+014	2 N-type, 2 P-Type		
6.00E+014	2 N-type, 2 P-Type		
9.00E+014	0		
1.50E+015		2 N-type, 2 P-Type	
2.50E+015		2 N-type, 2 P-Type	
4.00E+015		0	
6.25E+015			2 N-type, 2 P-Type
1.00E+016			2 N-type, 2 P-Type
1.60E+016			2 N-type, 2 P-Type
	•		



#### Current status at CERN

After

re-irradiation

Fluence n/cm <sup>2</sup>	320	200	120
4.00E+014	1 N-type, 1 P-Type		
6.00E+014	2 N-type, 2 P-Type		
9.00E+014	1 N-type, 1 P-Type		
1.50E+015		1 N-type, 1 P-Type	
2.50E+015		2 N-type, 2 P-Type	l
4.00E+015		1 N-type, 1 P-Type	
6.25E+015			1 N-type, 1 P-Type
1.00E+016			2 N-type, 2 P-Type
1.60E+016		ſ	1 N-type, 1 P-Type



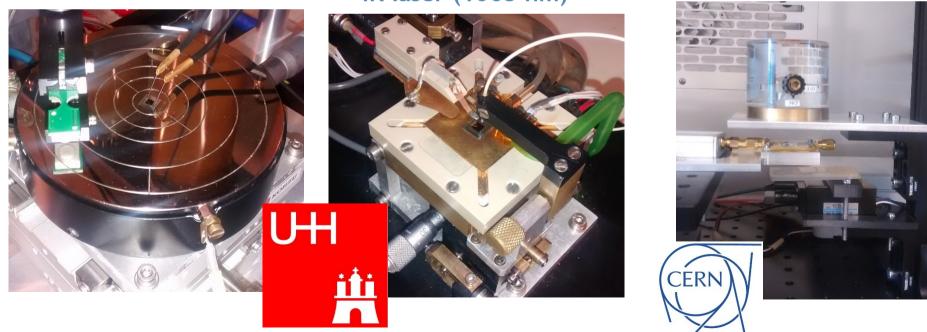
#### Properties to be measured:

- ✓ Bulk current I(U,  $\Phi$ , h) → power consumption, noise
- ✓ Capacitance (1 MHz signal):  $C(U, \Phi, h) \rightarrow capacitance$  seen by electronics (below ~50pF)
- ✓ Charge collection efficiency CCE(U,  $\Phi$ , thickness) → signal
- $\checkmark$  MIP sensitivity with beta source  $\rightarrow$  for calibration purpose and S/N
- Effect of annealing on the properties (up to 3 months at room temperature)

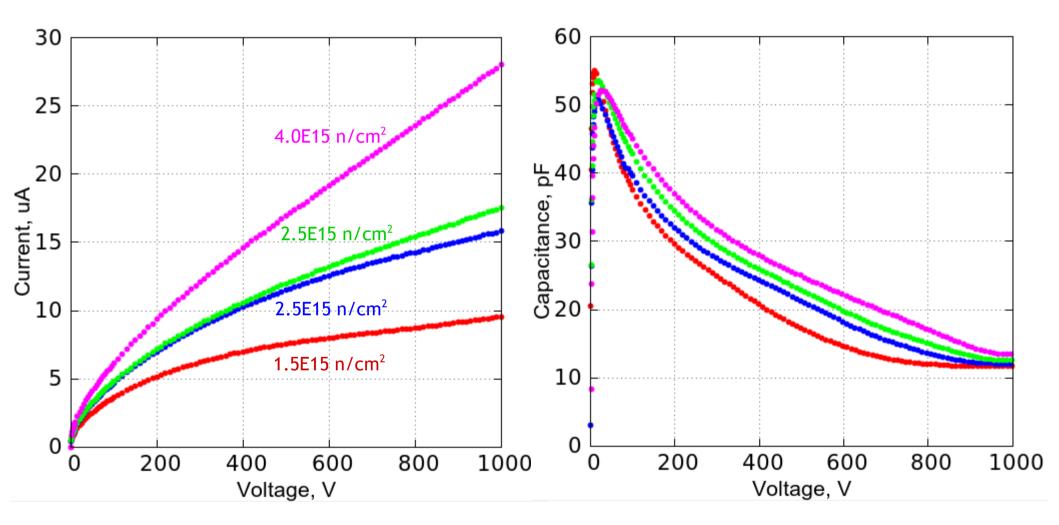
#### IV/CV set-up

#### TCT set-up for CCE IR laser (1063 nm)

#### MIP sensitivity with RS



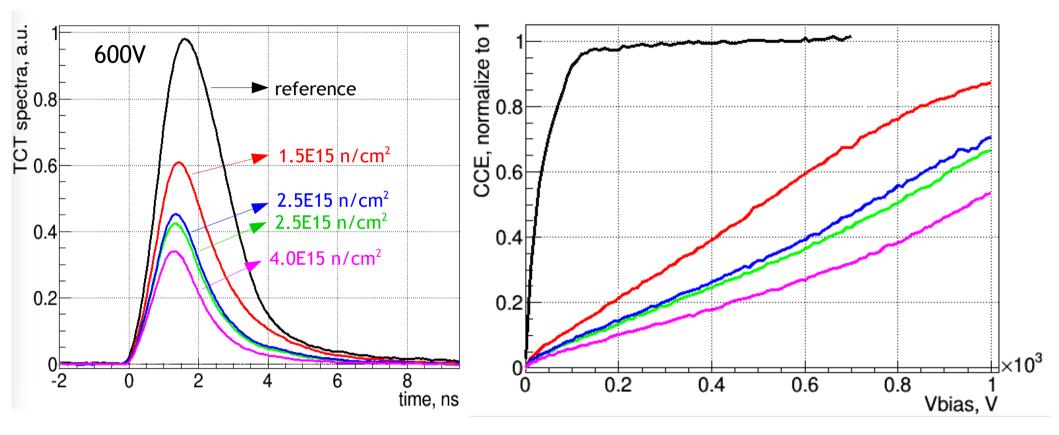
Examples of IV and CV measurements: FZ 200um N-type, at -20°C (455Hz for CV)



- ✓ The higher the fluence, the higher is the leakage current
- Higher is the fluence higher is the capacitance, depletion voltage increases with fluence --> capacitance increase.

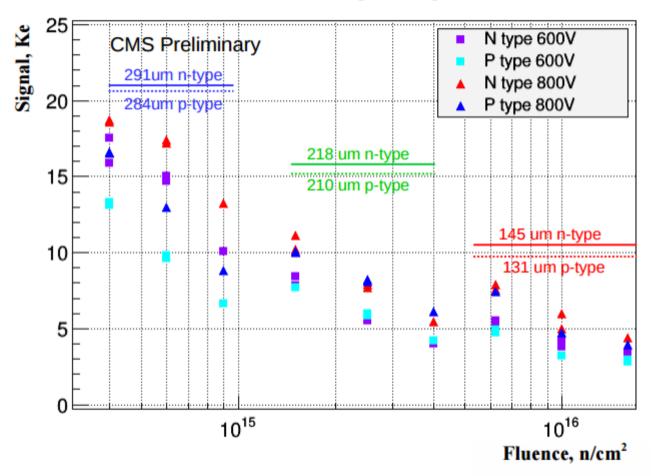


TCT measured at  $-20^{\circ}$ C, IR laser(1060 nm) pulse width: 50 ps, top illumination FZ 200um N-type



- Shorter pulse and rise time after irradiation --> relevant for timing
- Collection time < 10 ns</li>
- CCE lower after irradiation
- At these high fluences it is hard to estimate the depletion voltage, CCE is increasing with Vbias.

Signal normalized to 73e/um from CCE on pad sensors -20C, 1063nm, annealing 10min@60C

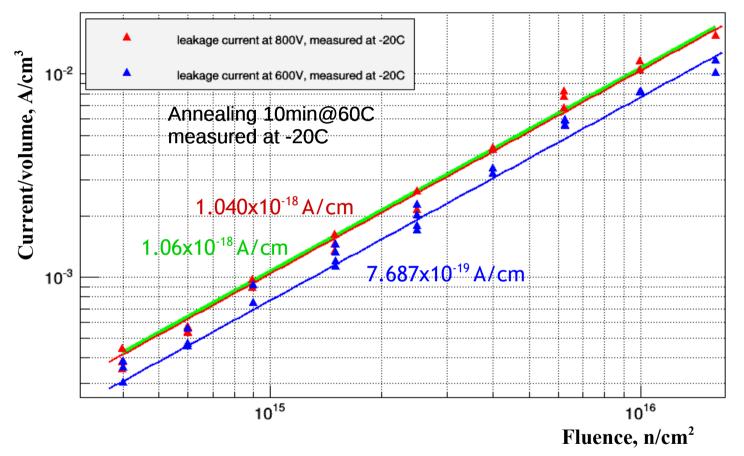


- ✓ Charge collection efficiency for  $\approx$  300 µm (leftmost set of points),  $\approx$  200 µm (middle set of points), and  $\approx$  120 µm silicon sensors (rightmost set of points).
- ✓ For 300 µm, low fluences, p-type diodes show lower values of CCE. For 200 µm and 120 µm both are closer.
- ✓ The lowest value of the charge measured is ~4.0/5.0 ke- for the nominal fluence (120 um). It is ~3.0/4.0 Ke- for ×1.5 the nominal, lower than expected, but still enough.



M. Moll's Thesis alpha value scaled to -20C: ~1.06x10<sup>-18</sup> A/cm

### Leakage current comparison



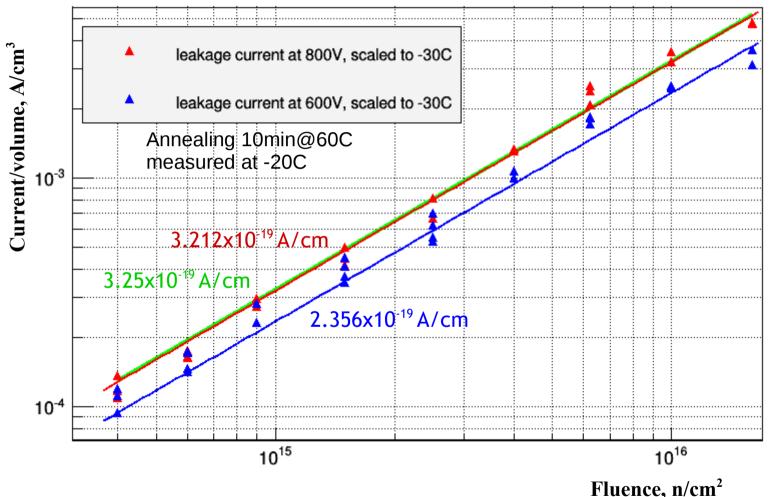
- Leakage current normalized by the volume of the diode (for all thicknesses and two type of bulk doping) increases proportional to the fluence
- The value measured at 800V is equal the alpha value given in the bibliography.
- Value at 600V a bit lower than expected.



 $\Delta I = \alpha \, \Phi_{eg} \, V$ 

M. Moll's Thesis alpha value scaled to  $-30^{\circ}$ C:  $-3.25 \times 10^{-19}$  A/cm

#### Leakage current comparison

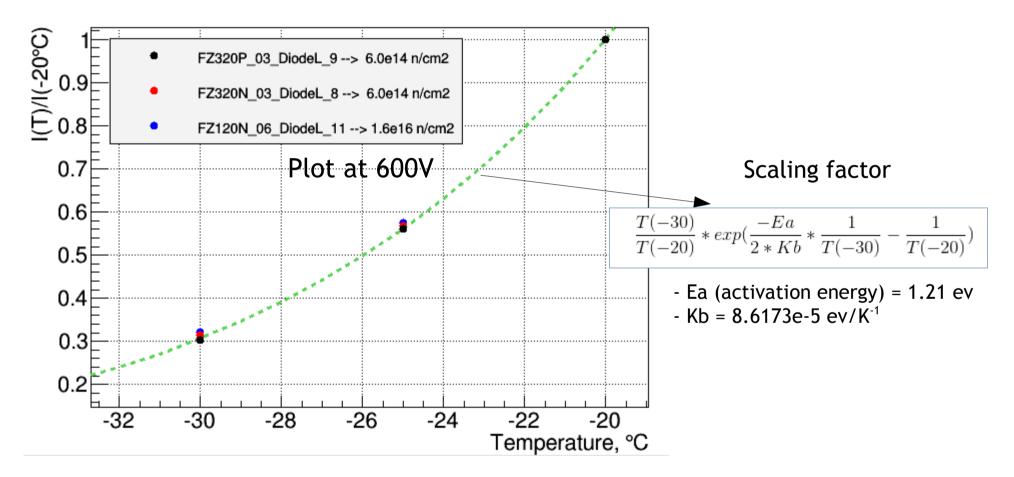


Same plot, but now scaled to  $-30^{\circ}$ C, closer to the operation temperature of the HGCAL.

✓ Same agreement, lower temperature --> lower values of the leakage current

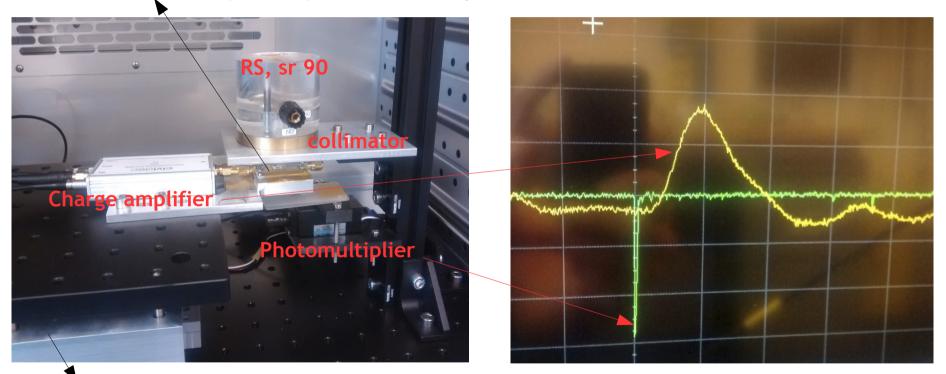


# Measurement of bulk current vs bias voltage (IV) as a function of the temperature (-20°C,-25°C,-30°C)



- Normalized to value of the current at -20°C
- Results are compatible between p-type and n-type
- Also compatible between different active thickness and different irradiation fluences
- ✓ The scale factor for the alpha value from -20℃ to -30℃ is in agreement with our measurements. Green curve shows the formula used to scale from -20 to -30℃.

# MIP sensitivity set-up $\rightarrow$ is ongoing, but it still needs extra work in order to get the first good measurements



Sensor (FZ120P) mounted on a pcb

XY stages --> allow the external positioning of the sensors inside the beam

- Example of one single signal given by the charge amplifier in yellow. The amplitude of this signal is
  proportional to the charge collected from the sensor after one MIP.
- Set-up inside a climatic chamber:
  - ✓ Operation temperature between  $-70^{\circ}$ C and  $180^{\circ}$ C
  - ✓ Humidity below 10% RH



## **Precision timing and test beam**

### Test of time response with Si PAD

#### General timing studies in CMS

- Vertex location to better than 1 cm in diphoton events from photon timing with 30 ps precision proven
- Event and object cleaning with 30 ps timing of vertices (from hits associated to charged tracks) and of showers studies ongoing
- Simulation studies with HGCAL
  - ✓ Single cell timing to O(100) ps possible with ToT electronics for deposits above about 30 MIPs
    - Photon and (high-energy) hadron shower timing to <30 ps from combined cells information

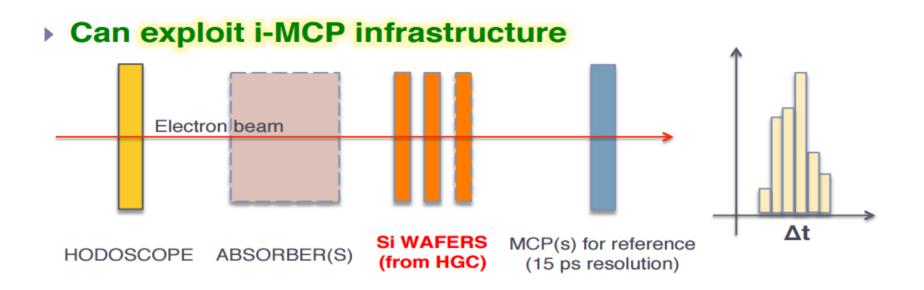
#### Proposed test of time response of Si PADs with beam

- Digitize pulses, emulate pulse discrimination offline, verify that the intrinsic detector jitter does not exceed few 10 ps.
- ✓ Implementation
  - Measure spread of the time difference between different wafers aligned along the beamline
  - Repeat measurements with variable absorbers in front to study the dependence on the number of MIPs



## **Precision timing and test beam**

#### Test of time response with Si PAD



### Test beam plan:

- $\checkmark$  Run w/o absorber or muons to calibrate response to MIPs
- Run with absorbers (available from zero to  $7X_0$ ):
  - Estimate <# of MIPs> from the signal amplitude relative to one MIP
  - Measure the time resolution as a function of MIPs multiplicity (<signal amplitude>)
  - There is enough precision in the electronics/DAQ to verify intrinsic jitters at the level of 10-20 ps.



# Summary and future activities

- ✓ Measurements after neutron irradiations of IV, CV and CCE done at Hamburg and crosschecked at CERN also with higher fluences and after the first step of annealing 10min@60°C
- CCE values and leakage current measured are in agreement with the expected values

### ✓ To do:

- ✓ Perform 80 min at 60°C additional annealing on the diodes (two weeks at room temperature) → repeat measurements
- ✓ Workshop for comparison of results with HPK campaign (and other data, lower fluence neutrons, but also protons...)
- ✓ First results with beta source coming soon  $\rightarrow$  for MIP sensitivity
- ✓ Precision timing test → ongoing

